

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

1. – 31. (cancelled)

32. (original) A peripheral card manufactured according to a process comprising the steps of:

adding circuit elements to a circuit board, said circuit board includes a set of test terminals;
testing one or more of said circuit elements using said test terminals; and

applying a conformal contact coating on a first surface of said circuit board to cover said test terminals and prevent access to said test terminals.

33. (original) A peripheral card according to claim 32, wherein:
said step of applying includes applying a liquid directly to a first surface of said circuit board.

34. (original) A peripheral card according to claim 32, wherein:
said step of applying includes applying a film directly to a first surface of said circuit board.

35. (original) A peripheral card according to claim 32, wherein:
said circuit board includes a first die mounted on said circuit board and a second die mounted on said first die;

said first die includes a flash memory array and said second die includes a controller;
said first die is wire bonded to said circuit board; and
said second die is wire bonded to said circuit board.

36. (original) A peripheral card according to claim 32, wherein:
said circuit board includes a conductive layer;
a first portion of said conductive layer forms said test terminals;

a second portion of said conductive layer forms user terminals;
said user terminals are positioned on an outside surface of said peripheral card; and

said circuit elements are encapsulated by a transfer mold process without covering said test terminals.

37. (original) A peripheral card according to claim 32, wherein:
said peripheral card is a memory card.

38. (original) A peripheral card, comprising:
a circuit board;
circuit elements on said circuit board;
a set of user terminals on said circuit board, said user terminals are in communication with at least a subset of said circuit elements;
a set of test terminals on said circuit board, said test terminals are in communication with one or more of said circuit elements;
an enclosure that covers a portion of said circuit board and said circuit elements without covering said set of user terminals and said set of test terminals; and
a conformal contact coating on a first surface of said circuit board covering said test terminals and preventing access to said test terminals.

39. (original) A peripheral card according to claim 38, wherein:
said conformal contact coating is applied as a liquid directly to said first surface of said circuit board.

40. (original) A peripheral card according to claim 38, wherein:
said conformal contact coating includes a film that is applied directly to said first surface of said circuit board.

41. (original) A peripheral card according to claim 38, wherein:

said circuit elements board include a first die mounted on said circuit board and a second die mounted on said first die.

42. (original) A peripheral card according to claim 41, wherein:
said first die is wire bonded to said circuit board; and
said second die is wire bonded to said circuit board.

43. (original) A peripheral card according to claim 42, wherein:
said first die includes a flash memory array and said second die includes a controller.

44. (original) A peripheral card according to claim 41, wherein:
said first die includes a flash memory array and said second die includes a controller.

45. (original) A peripheral card according to claim 38, wherein:
said circuit board includes a conductive layer;
a first portion of said conductive layer forms said test terminals;
a second portion of said conductive layer forms said user terminals; and
said user terminals are positioned on an outside surface of said peripheral card.

46. (original) A peripheral card according to claim 38, wherein:
said peripheral card is a memory card.

47. (original) A method performed for a peripheral card, comprising the steps of:
testing one or more circuit elements of a first peripheral card using one or more test terminals of said first peripheral card; and
covering said test terminals with a conformal contact coating in order to prevent access to said test terminals.

48. (original) A method according to claim 47, wherein:
said step of covering includes applying a liquid directly to said first peripheral card.

49. (original) A method according to claim 47, wherein:
said step of covering includes applying a film directly to said first peripheral card.

50. (original) A method according to claim 47, wherein:
said circuit elements include a flash memory array.

51. (original) A method according to claim 47, wherein:
said first peripheral card is a memory card.